



Press Release

Infineon EMV Payment Solutions Help Fight Financial Fraud

Las Vegas, NV – May 13, 2014 – Infineon Technologies North America today introduced Macchiato, a Java Card based payment solution family of security controllers optimized for [EMV](#)[®] (Europay, MasterCard and Visa)-compliant payment card applications in the U.S. With the full EMV certification, and both Visa and MasterCard payment applets as well as Java Operating System integrated on the chip, the Macchiato EMV payment solutions provide card issuers, card manufacturers and merchants with a cost-effective route to implement migration projects on a chip platform with higher security, better quality and reliability. The solutions also simplify and accelerate the required approval process.

EMV is a global standard for smart, secure payment networks overseen by the public corporation EMVCo LLC. Financial institutions in the U.S. are migrating from magstripe payment cards to the EMV-compliant smart cards to achieve a higher level of security in financial transactions and reduce the risk of fraud. For the financial institution to issue EMV compliant cards, the issuer must assure compliance with security requirements of the card itself and the applications used by the card. The Macchiato family provides card issuers with an “EMV-ready” solution that offers a fast and easy personalization process and superior end-user satisfaction, combined with simple manufacturing process for card manufacturers based on innovative assembly technology for dual-interface versions of the chip.

Over 25 years, Infineon has developed innovative solutions in hardware-based security, and has been the global market leader for 15 consecutive years. Infineon supplies about one-third of the chips used in smart payment cards worldwide according to ABI Research (May 2013 report).

“More than 40 million smart cards based on Infineon security controllers have shipped to U.S. customers in the most recent two calendar quarters, making us one of the top suppliers for the EMV card migration,” said Joerg Borchert, vice

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president of the Chip Card and Security group at Infineon Technologies North America. “We’re committed to supporting the industry’s transition to the global standard with a chip portfolio that offers superior performance, high reliability for long-life of the consumer’s smart card, and unsurpassed security.”

Macchiato EMV Payment Solutions Features and Performance

The Infineon Macchiato EMV payment solutions are based on the company’s field-proven SLE77 SOLID FLASH™ security microcontroller. Running Java Card OS, each chip in the family is VGP 2.2.1 and GlobalPlatform 2.1.1 compliant. Different versions support either SDA (Static Data Authentication) or dual SDA/DDA (Dynamic Data Authentication) and card issuers can choose either a contact-only interface or dual-interface (contact/contactless).

Available only from Infineon, the EMVCo approved SOLID FLASH SLE77 product family gives developers and card issuers the flexibility to update, test and validate on-chip applications and firmware without the cost and cycle-time limitations of less advanced, ROM-based chip card programming.

The dual-interface version of the chip family features Infineon’s innovative CoM (Coil on Module) packaging technology. The numerous benefits offered by this inductive coupling technology include state-of-the-art contactless performance, improved robustness and reliability of the assembled card as well as a significantly higher card manufacturing and personalization yields resulting in lower card manufacturing costs.

Product Data and Availability

Infineon Macchiato EMV payment family devices are available now. Contact interface versions are mainly shipped in black line flip packages. The dual interface CoM assembled module contains both the processor and the requisite first antenna, while the secondary antenna is optionally available as an etched or wired inlay solution.

More information about the Infineon EMV payment solution is available at www.infineon.com/payment

About Infineon

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Infineon Technologies AG, Neubiberg, Germany, offers semiconductor and system solutions addressing three central challenges to modern society: energy efficiency, mobility and security. In the 2013 fiscal year (ending September 30th), the Company reported sales of Euro 3.84 billion with around 26,700 employees worldwide. Infineon is listed on the Frankfurt Stock Exchange (ticker symbol: IFX) and in the USA on the over-the-counter market OTCQX International Premier (ticker symbol: IFNNY). Further information is available at www.infineon.com

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This press release is available online at www.infineon.com/emv_pressrelease



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